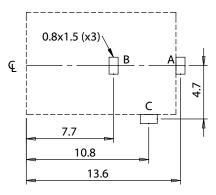
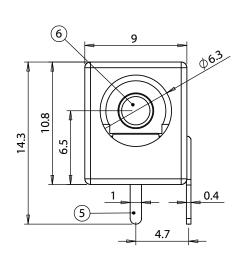
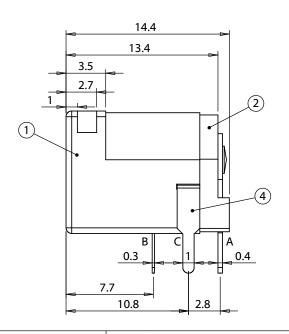


SECTION A-A

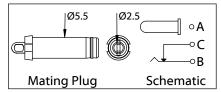


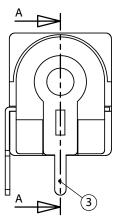
P.C.B. Layout











Revision:	Date:	Description:	Prepared:	Notes:							
Α	5/20/2019	Initial release		Function test: no open, no shor	t circuit, no		$\vdash$ l	NSII	ITY		
			Verified:	intermittent		. — 10. — .					
						tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com					
			Dimensions are in								
			millimeters.	Description:	Size: Part number: A 54-00134						
			Tolerances: < 1.0: ± 0.1 mm	Connector, dc jack 5.5x2.5 mm, PCB mount, 90°, silver plated, thru hole							
			1.0 to 10.0: ± 0.2 mn > 10.0: ± 0.3 mm			Scale:	3:1		Sheet 1 of 2		

5 4 3 2

## Ratings

Maximum operating voltage: 48 V

Maximum operating current: 6.0 A (not mated under load)

#### **Operating Temperature Range**

-25 to 85 °C, relative humidity of 85% or less

#### Materials

1)Insulator: PBT, black

(2)Cover: PBT, black

(3)Terminal: brass, silver plated

(4)Terminal: brass, silver plated

(5) Spring contact: phosphor bronze, silver plated

(6)Center pin: brass, nickel plated

### **Electrical Requirements**

Dielectric strength: 1 min @ 500 Vac

Insulation resistance: 100 MΩ @ 500 Vdc minimum

Contact resistance: 50 mΩ maximum

### **Mechanical Requirements**

Insertion force: 0.3-1.5 kaf

Withdrawal force: 0.3-1.5 kgf

Life cycle: 5000 mating cycles while maintaining contact resistance: 100 mΩ maximum, insulation resistance: 50 M

minimum, withstand voltage: 500 Vac, 1 min

Terminal strength: 300 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and without damage or excessive looseness of terminals

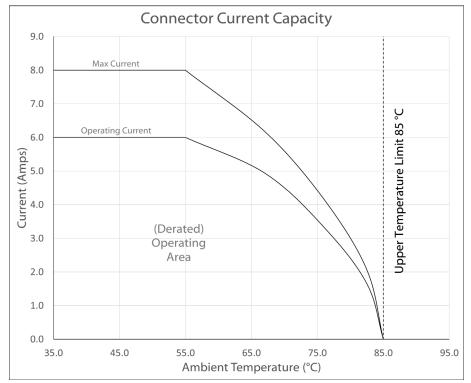
## Soldering

Solderability: 75% minimum coverage when terminals dipped 2mm in 245 ±5 °C solder bath for 3 ±0.5 seconds

Solder bath durability: no deformation when immersed in 255 ±5 °C up to surface of the board 1.6 mm for 5 seconds or less Solder iron durability: no deformation when exposed to  $350 \pm 10$  °C

for 3 ±0.5 seconds

**Environmental Requirements** Cold test: -25 ±3 °C for 48 hours without deformation Heat test: 85 ±2 °C, for 48 hours without deformation Humidity test: 40 ±2 °C, relative humidity 90-95% for 48 hours without deformation



Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings, mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation.

# **Wave Soldering Temperature Profile**

Pb - Free Flow Profile

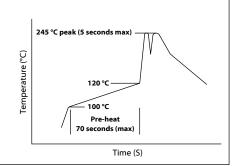
Solder temperature: 245 °C

Time: 5 seconds maximum

Pre-heat: 100 ~120°C

Time: 70 seconds maximum

Measure point: surface of the solder leads



Revision:	Date:	Description:	Prepared:	Notes:							
Α	5/20/2019	Initial release		Function test: no open, no shor	t circuit, no			NSII.	ITY		
			Verified:	intermittent		tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com					
			Dimensions are in				10X 1.341.323.4202 Web terisinty.com				
			millimeters. Tolerances:	Description:  Connector, dc jack 5.5x2.5 mm, PCB mount, 90°, silver plated, thru hole		Size: Part number:					
			< 1.0: ± 0.1 mm			Α	54-00	54-00134			
			1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm			Scale	: 5:1		Sheet 2 of 2		